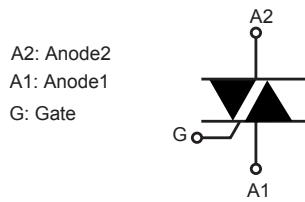
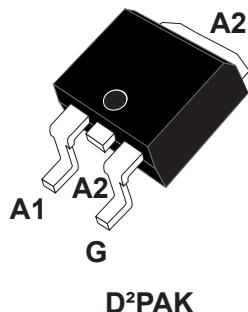


### 16 A - 800 V - D<sup>2</sup>PAK Snubberless™ Triac



## Features

- High static dV/dt
- High dynamic turn-off commutation (dI/dt)c
- 150 °C maximum junction temperature
- Three quadrants
- Surge capability  $V_{DSM}$ ,  $V_{RSM} = 900$  V
- Benefits:
  - High immunity to false turn-on thanks to high static dV/dt
  - Improved turn-off in high temperature environments thanks higher (dI/dt)c
  - Increase of thermal margin due to extended working  $T_j$  up to 150 °C
  - Good thermal resistance due to non-insulated tab.

## Applications

- General purpose AC line load switching
- Motor control circuits
- Home appliances
- Heating
- Lighting
- Inrush current limiting circuits
- Overvoltage crowbar protection

### Product status link

[T1635T-8G](#)

### Product summary

$I_{T(RMS)}$	16 A
$V_{DRM}/V_{RRM}$	800 V
$V_{DSM}/V_{RSM}$	900 V
$I_{GT}$	35 mA

## Description

Available in SMD, the T1635T-8G Triac can be used for the on/off or phase angle control function in general purpose AC switching where high commutation capability is required. The [T1635T-8G](#) can be used without a snubber RC circuit when the limits defined are respected.

D<sup>2</sup>PAK package is UL-94,V0 flammability resin compliance.

Package environmentally friendly Ecopack®2 graded (RoHS and Halogen Free compliance).

Snubberless™ is a trademark of STMicroelectronics.

# 1 Characteristics

**Table 1. Absolute maximum ratings (limiting values)**

Symbol	Parameter	Value	Unit
$I_{T(RMS)}$	RMS on-state current (full sine wave)	16	A
$I_{TSM}$	Non repetitive surge peak on-state current (full cycle, $T_j$ initial = 25 °C)	$t_p = 20$ ms	120
		$t_p = 16.7$ ms	126
$I^2t$	$I^2t$ value for fusing	$t_p = 10$ ms	$A^2s$
$dI/dt$	Critical rate of rise of on-state current, $I_G = 2 \times I_{GT}$ , $t_r \leq 100$ ns	$T_j$ initial = 150 °C, $f = 100$ Hz	100 A/ $\mu$ s
$V_{DRM}/V_{RRM}$	Repetitive peak off-state voltage (50-60 Hz)	$T_j = 125$ °C	800 V
		$T_j = 150$ °C	600 V
$V_{DSM}/V_{RSM}$	Non Repetitive peak off-state voltage	$t_p = 10$ ms, $T_j = 25$ °C	900 V
$I_{GM}$	Peak gate current		4 A
		$t_p = 20$ $\mu$ s, $T_j = 150$ °C	5 V
$V_{GM}$	Peak Gate Voltage		
$P_{G(AV)}$	Average gate power dissipation	$T_j = 150$ °C	1 W
$T_{stg}$	Storage junction temperature range		-40 to +150 °C
$T_j$	Operating junction temperature range		-40 to +150 °C

**Table 2. Electrical characteristics ( $T_j = 25$  °C, unless otherwise specified)**

Symbol	Test conditions	Quadrants; $T_j$		Value	Unit
$I_{GT}^{(1)}$	$V_D = 12$ V, $R_L = 30$ Ω	I - II - III	Max.	35	mA
$V_{GT}$	$V_D = 12$ V, $R_L = 30$ Ω	I - II - III	Max.	1.3	V
$V_{GD}$	$V_D = 600$ V, $R_L = 3.3$ kΩ	$T_j = 150$ °C	I - II - III	0.2	V
$I_L$	$I_G = 1.2 \times I_{GT}$	I - III	Max.	55	mA
		II	Max.	65	mA
$I_H^{(2)}$	$I_T = 500$ mA, gate open		Max.	45	mA
$dV/dt^{(2)}$	$V_D = 536$ V, gate open	$T_j = 125$ °C	Min.	2000	V/ $\mu$ s
	$V_D = 402$ V, gate open	$T_j = 150$ °C	Min.	1000	V/ $\mu$ s
$(dI/dt)c^{(2)}$	Without snubber	$T_j = 125$ °C	Min.	16	A/ms
		$T_j = 150$ °C	Min.	12	A/ms

1. Minimum  $I_{GT}$  is guaranteed at 5% of  $I_{GT}$  max

2. For both polarities of A2 referenced to A1.

**Table 3. Static characteristics**

Symbol	Test conditions	T <sub>j</sub>		Value	Unit
V <sub>TM</sub> <sup>(1)</sup>	I <sub>TM</sub> = 22.6 A, t <sub>p</sub> = 380 µs	25 °C	Max.	1.6	V
V <sub>TO</sub> <sup>(1)</sup>	Threshold on-state voltage	150 °C	Max.	0.85	V
R <sub>D</sub> <sup>(1)</sup>	Dynamic resistance	150 °C	Max.	34	mΩ
I <sub>DRM</sub> /I <sub>RRM</sub>	V <sub>DRM</sub> = V <sub>RRM</sub> = 800 V	25 °C	Max.	5	µA
		125°C		1.0	mA
	V <sub>DRM</sub> = V <sub>RRM</sub> = 600 V	150 °C	Max.	3.6	mA

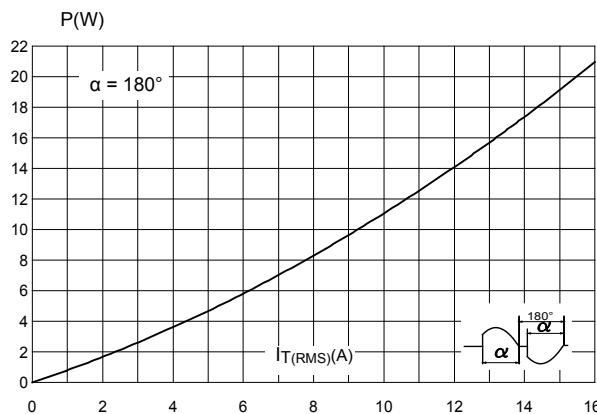
1. For both polarities of A2 referenced to A1.

**Table 4. Thermal resistance**

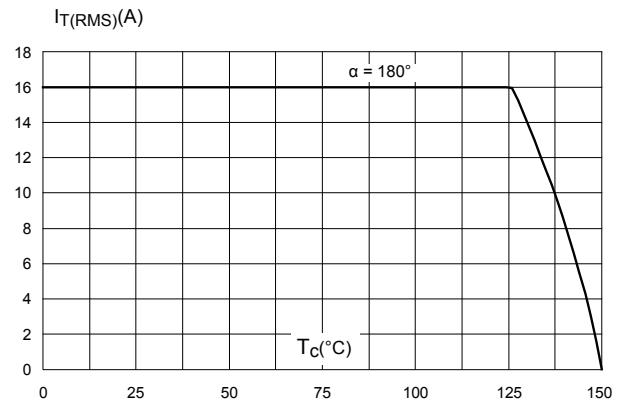
Symbol	Parameter		Value	Unit
R <sub>th(j-c)</sub>	Junction to case (AC)	D <sup>2</sup> PAK	Max.	1.15 °C/W

## 1.2 Characteristics curves

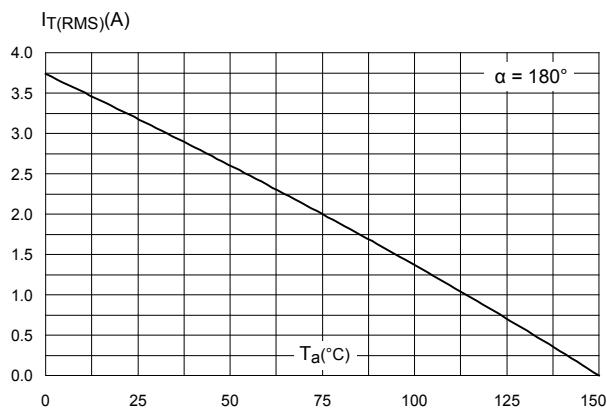
**Figure 1. Maximum power dissipation versus on-state RMS current (full cycle)**



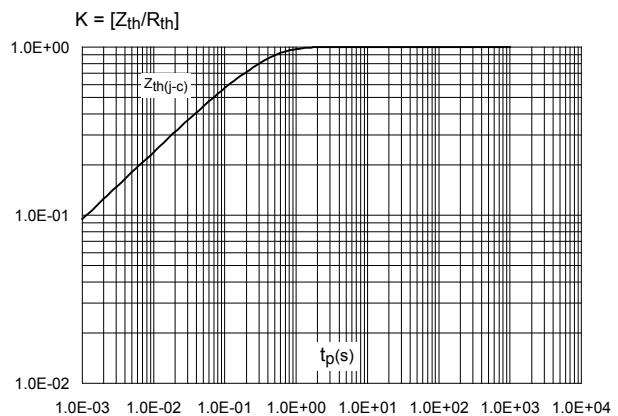
**Figure 2. On-state RMS current versus case temperature (full cycle)**



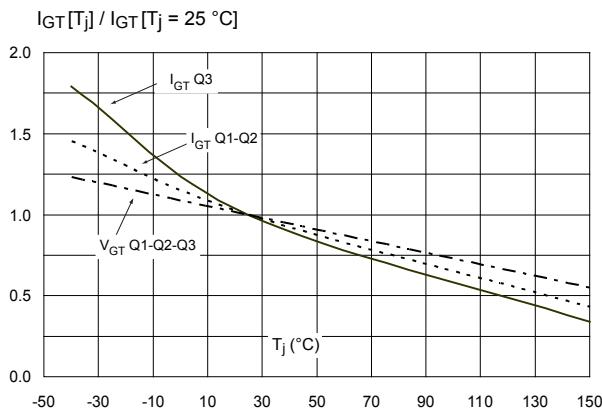
**Figure 3. On-state RMS current versus ambient temperature (free air convection)**



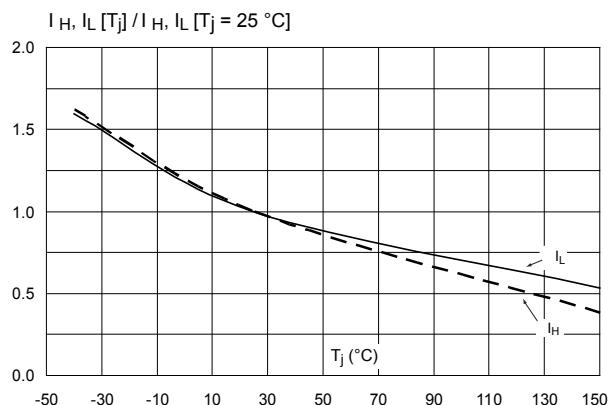
**Figure 4. Relative variation of thermal impedance versus pulse duration**



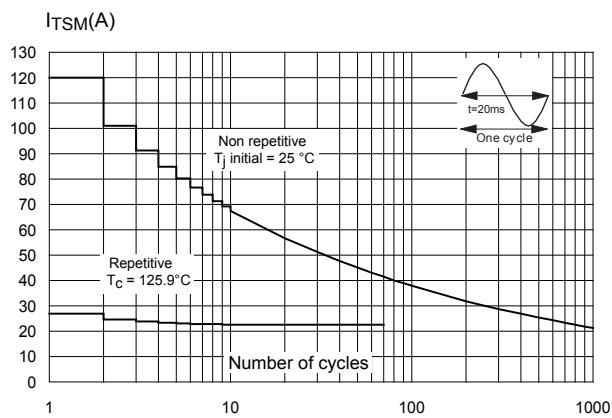
**Figure 5. Relative variation of gate trigger voltage and current versus junction temperature (typical values)**



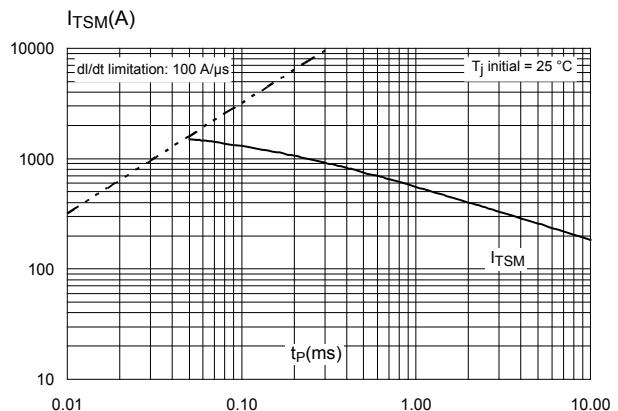
**Figure 6. Relative variation of holding current and latching current versus junction temperature (typical values)**



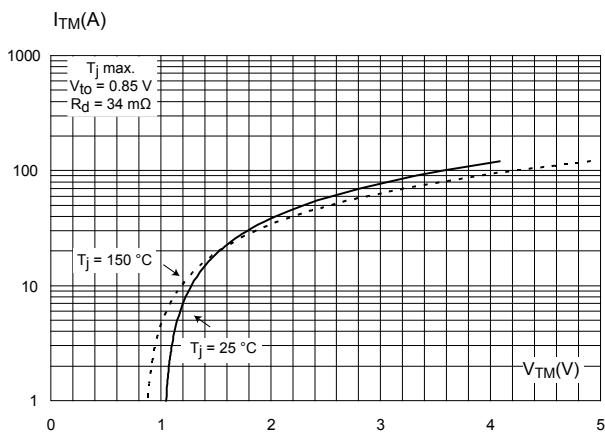
**Figure 7. Surge peak on-state current versus number of cycles**



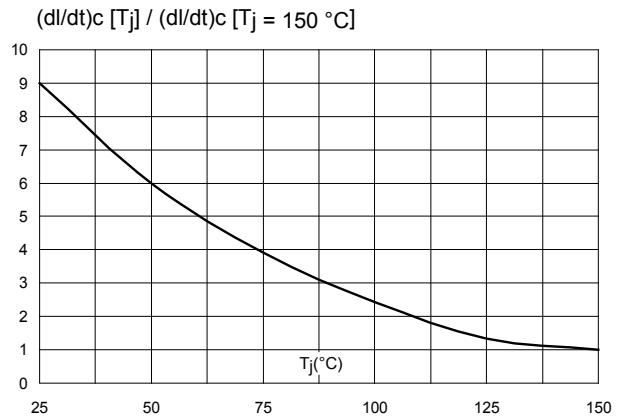
**Figure 8. Non repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 10$  ms**



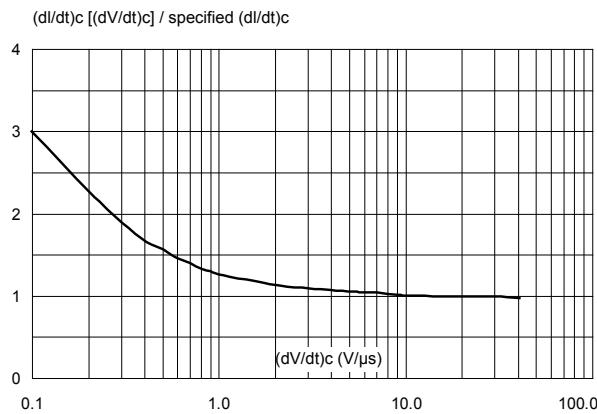
**Figure 9. On-state characteristics (maximum values)**



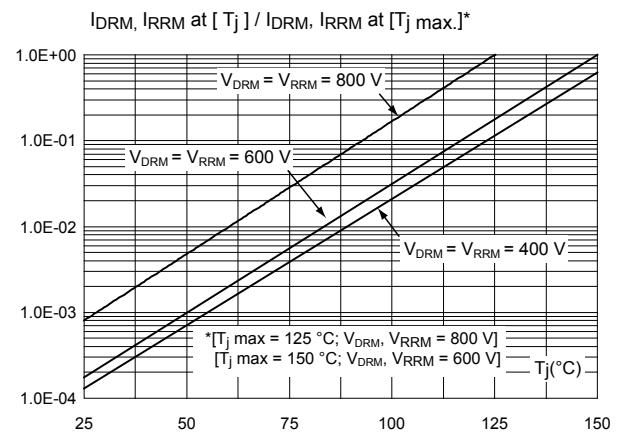
**Figure 10. Relative variation of critical rate of decrease of main current versus junction temperature (typical values)**



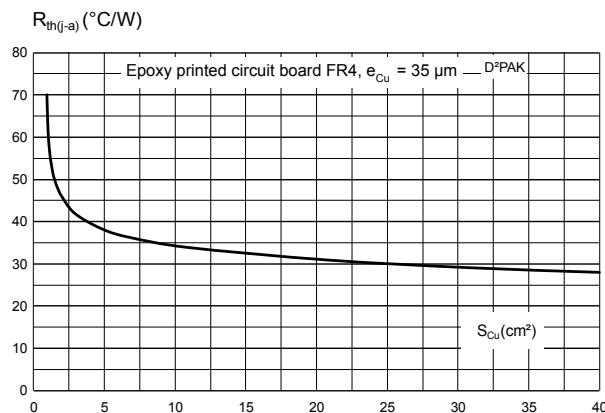
**Figure 11. Relative variation of critical rate of decrease of main current versus reapplied  $(dV/dt)c$  (typical values)**



**Figure 12. Relative variation of leakage current versus junction temperature for different values of blocking voltage (typical values)**



**Figure 13. Thermal resistance junction to ambient versus copper surface under tab**



## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 2.1 D<sup>2</sup>PAK package information

- ECOPACK®2 compliant
- Lead-free package leads finishing
- Molding compound resin is halogen-free and meets UL94 standard level V0

Figure 14. D<sup>2</sup>PAK package outline

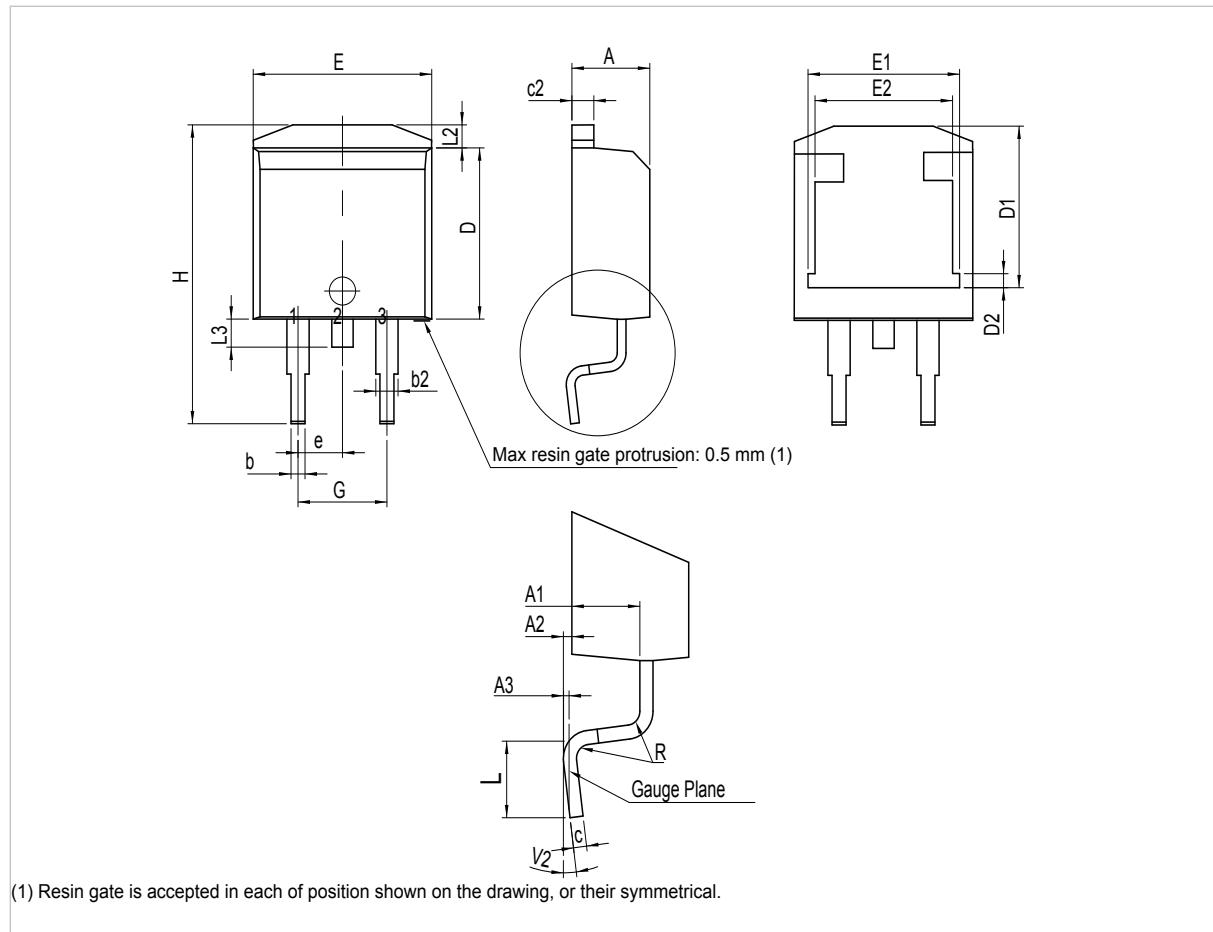


Table 5. D<sup>2</sup>PAK package mechanical data

Ref.	Dimensions					
	Millimeters			Inches <sup>(1)</sup>		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.30		4.60	0.1693		0.1811
A1	2.49		2.69	0.0980		0.1059
A2	0.03		0.23	0.0012		0.0091
A3		0.25			0.0098	
b	0.70		0.93	0.0276		0.0366
b2	1.25		1.7	0.0492		0.0669
c	0.45		0.60	0.0177		0.0236
c2	1.21		1.36	0.0476		0.0535
D	8.95		9.35	0.3524		0.3681
D1	7.50		8.00	0.2953		0.3150
D2	1.30		1.70	0.0512		0.0669
e		2.54			0.1	
E	10.00		10.28	0.3937		0.4047
E1	8.30		8.70	0.3268		0.3425
E2	6.85		7.25	0.2697		0.2854
G	4.88		5.28	0.1921		0.2079
H	15		15.85	0.5906		0.6240
L	1.78		2.28	0.0701		0.0898
L2	1.27		1.40	0.0500		0.0551
L3	1.40		1.75	0.0551		0.0689
R		0.40			0.0157	
V2 <sup>(2)</sup>	0°		8°	0°		8°

1. Dimensions in inches are given for reference only

2. Degree

Figure 15. D<sup>2</sup>PAK recommended footprint (dimensions are in mm)

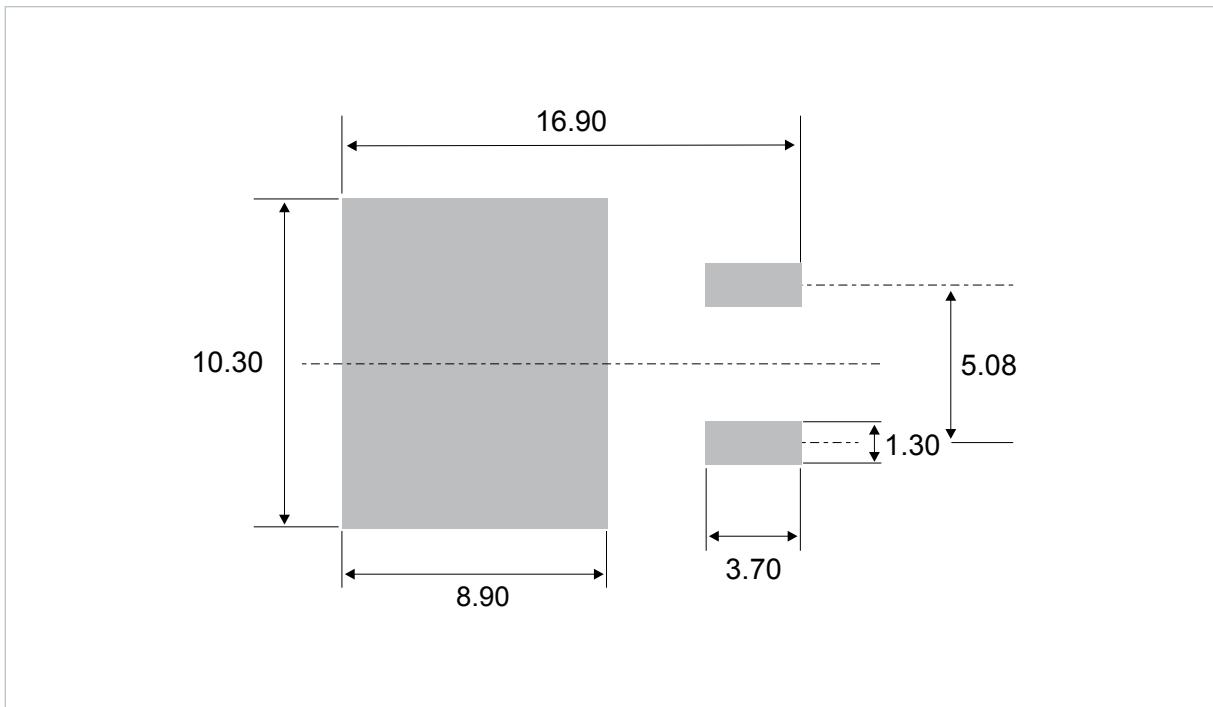
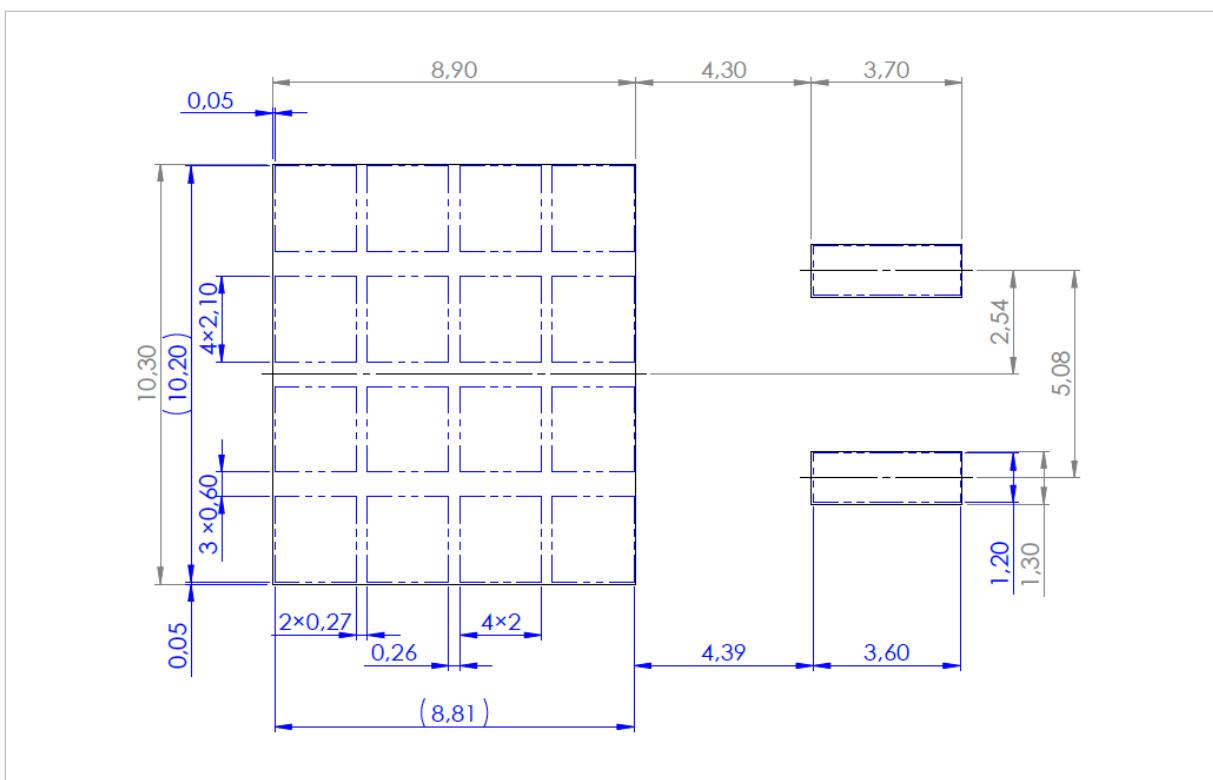


Figure 16. D<sup>2</sup>PAK stencil definitions(dimensions are in mm)



### 3 Ordering information

Figure 17. Ordering information scheme

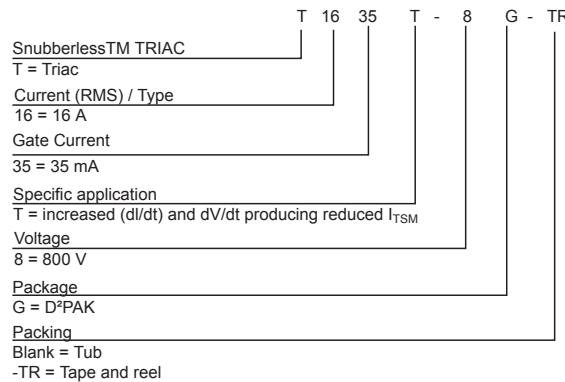


Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
T1635T-8G-TR	T1635T-8G	D²PAK	1.6 g	1000	Tape and reel
T1635T-8G				50	Tube

## Revision history

**Table 7. Document revision history**

Date	Version	Changes
12-Sep-2018	1	Initial release.

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